

Announcement and Call for Abstracts Topical Workshop on **Engineered Micro Systems & Devices**

This workshop is being held as a part of the Device Packaging Conference

Radisson Fort McDowell Resort

Fountain Hills, Arizona - USA

March 4 - 7, 2019

Technical Co-Chair:	Technical Co-Chair:	Technical Co-Chair:
Dr. Robert Dean , Auburn University deanron@auburn.edu	Dr. Li-Anne Liew , CU Boulder / NIST li-anne.liew@nist.gov	Dr. Aubrey Beal , US Army AMRDEC aubreybeal@gmail.com

Engineered Micro Systems & Devices Organizing Committee:

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Engineered Micro Systems & Devices Workshop Focus:

The objective of the Engineered Micro Systems & Devices Workshop is to have a unique forum that brings together scientists, engineers, manufacturers, academia, and business people from around the world who have been working in the area of engineered miniaturized systems. Topics include prognostics, advanced sensors, MEMS/NEMS/MOEMS, additive manufacturing, wireless devices, photonics, quantum devices, power electronics, and other miniaturized electronic and/or mechanical systems and devices for which advanced packaging is a key element.

Abstracts are being requested on the following topics:

- GHz & THz Devices
- Flexible/Conformal Micro Systems
- Microfluidics & Bio-Medical Devices
- Prognostics
- MEMS/NEMS/MOEMS Devices & Systems
- Photonics & Quantum Devices
- Photovoltaics & Power Electronics
- Sensors & Actuators
- Organic Electronics
- Innovative Materials and Processing
- Counterfeit Component Detection
- Additive Manufacturing
- Wireless Micro Devices
- Energy Scavenging & Power Electronics
- Harsh Environment Devices/Systems
- LCDs & LEDs/OLEDs
- Environmental Sensors & Applications
- IoT Devices & Systems

Those wishing to present in the Device Packaging Conference must submit a 300-500 word abstract electronically **no later than October 26, 2018**, using the on-line submittal form at: www.imaps.org/abstracts.htm. No formal technical paper is required. A reproduction-ready two- to four-page concise summary with text (figures and graphs included if necessary) will be required for the abstract booklet on Friday, January 26, 2018. A post-conference USB containing the full presentation material as supplied by authors will be mailed 15 business days after the event to all attendees. Please contact Brian Schieman by email at bschieman@imaps.org if you have questions. **STUDENT AUTHORS:** upon abstract submission, please select “**yes, I’m a full-time student**” on the form and you will automatically be entered in the student competition with \$3000 in foundation awards (\$1500 1st, \$1000 2nd, \$500 3rd).

Device Packaging Exhibit and Technology Show:

IMAPS will hold a concurrent exhibition for vendors and suppliers who support the many aspects of **Micro Systems & Devices**. This venue features an ideal atmosphere to showcase your products and services to key decision making professionals in the industry. Full 8' by 10' exhibit spaces will be available. To reserve booth space please fill out the on-line submittal form before December 1, 2018 at: www.imaps.org/devicepackaging or contact Brian Schieman by email at bschieman@imaps.org.

Device Packaging Professional Development Courses (PDCs):

For those wishing to broaden their knowledge of device packaging, a selection of half-day courses will be offered on Monday, March 5th, preceding the technical conference. If you would like to participate as an instructor, please submit a description of your short course on-line at www.imaps.org/pdc **no later than October 26, 2018**.